

AMENDMENTS

IN THE CLAIMS:

Cancel Claim 1.

Add new Claims 2-6, as follows:

1  
2. A method of making an electronic surface mount package, the method comprising the steps for:  
forming a package having a side wall with a bottom end;  
encapsulating a plurality of toroid transformers within the package with a resilient material;  
molding a plurality of terminal pins within the side wall, each of the pins extending through the side wall and having a solder post end, each of the post ends extending beyond the bottom end of the side wall; and  
wrapping and soldering the wires from the transformers to the solder post ends for each of the pins.

2  
3. The method of claim 2 wherein the resilient material is a soft silicone material.

3  
4. A method of making an electronic surface mount package, the method comprising the steps for:

molding a one piece construction package having a side wall with a bottom end and a plurality of terminal pins within and extending from the bottom of the package;  
encapsulating and carrying a plurality of toroid transformers within the package; and  
wrapping and soldering the wires from the transformers to an end of a solder post for each of the pins.

4  
5. The method of claim 4 wherein the step for encapsulating and carrying the plurality of toroid transformers pours a resilient material into the package and subsequently sets the resilient material.

5  
6. The method of claim 5 wherein the resilient material is a soft silicone material.